# CMS Binary Chip development for the Outer Tracker High-Luminosity Upgrade

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# Outline

- Background
- CBC2 Features
- CBC2 Testing
- Future work
- Summary & Conclusion

# Phase-II Upgrade of the CMS Strip Tracker



- Baseline design: Barrel+5Endcaps
- Based on 2 module types only
- Provides at the same time:
  - *readout data* upon receipt of L1 trigger
  - trigger data @40MHz



# **Basic Trigger Module Concept**



16 April 2014 A. Honma, Phase2 Outer Tracker Upgrade ElectronicsMeeting 5

# **High Pt Track Identification Concept**



- High-PT tracks (stubs) can be identified if cluster centre in top layer lies within a search window in R-Φ (rows)
- $p_T$  cut given by: module radius (z), sensor separation and correlation window

## **First Version: CBC Main Features**

- IBM 130nm CMOS process
- binary, unsparsified architecture
  - retains chip and system simplicity
  - but no pulse height data
- designed for ~2.5 5cm  $\mu$ strips < ~10 pF
- 128 channels, 50  $\mu m$  pitch wire-bond
  - either polarity input signal
- not contributing to L1 trigger
- powering test features:
  - 2.5 -> 1.2 DC-DC converter
  - LDO regulator (1.2 -> 1.1) feeds analogue FE
- fast (SLVS) and slow (I2C) control interfaces



# **CBC(1) Test Results**

e.g. for 5pF input capacitance:

noise: ~ 800 e<sub>RMS</sub>

total power: < 300 μW/channel

see: "M.Raymond et al 2012 JINST 7 C01033" "W.Ferguson et al 2012 JINST 7 C08006"





#### beam profile

APV plane

CBC sensor



## **CBC** $\rightarrow$ **CBC2**: New Features

**BOND** 250µm pitch C4 layout

**WIRE** 

**PADS** (for commercially assembled module)

- 254 channels for 127 + 127 strips
- Vetoes of wide clusters
- Correlation logic for stub formation
- Front-end circuit improvements
- On-chip test pulse circuit with DLL for timing adjustment
- 4 bit direct input for controls (T1 trigger, Fast reset, Test pulse & I2C refresh)
- Analogue Multiplexer for bias monitoring
- Improved DC-DC (CERN)
- Back edge wire-bond pads for wafer probe
- Received Jan 2013 fully functional

# **Analogue Front End**

## **CBC2 Front End Specifications**

Detector Type:	Silicon Strip
Signal Polarity:	both (electrons and holes)
Strip length:	2.5 – 5cm
Strip Capacitance:	< 10pF
Coupling:	AC or DC
Detector leakage:	up to 1uA leakage current compensation
Noise:	<1000e <sup>-</sup> <sub>RMS</sub> for 5pF sensor capacitance
Overload recovery:	normal response within ~ 2.5µs after 4pC signal
Power:	~500μW / channel (for 5pF strips)
Power supply:	1.1 V (front end supplied through LDO to get supply noise rejection)
Gain	50mV/fC
Dynamic range:	Linear up to 4fC
Timewalk:	<16ns for 1.25fC and 10fC signals with comp. thresh. set at 1fC

## **CBC 2 Front End**



# **Digital Back End**





### **Data buffer and Readout**

- 256-deep memory  $\rightarrow$  max 6.4µs L1 trigger latency
- Dual-port SRAM (SEU considered tolerable for data)
- 32-deep additional buffer for events awaiting readout
- Data serialized in 266 bit long packets



- Write and Read pointers separated by programmable latency
- 2 error bits:

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- Monitor the difference between Wr/Rd pointers against programmed latency
- Buffer overflow
- The address of the trigger counter is also a useful way to check the synchronization of different chips on the module
- Liu-Whitaker SEU-hardened Flip Flops for control logic

# **Stub Finding Logic**



# **CBC2** Test Activities

## **CBC2 Test Activities**

### Wire-bond CBC2

- Useful to develop wafer probe procedures
- X-rays TID testing

### 2xCBC2 hybrid

- Hybrid characterization and chip integration
- Bump-bonded ASICs
- Inter-chip links & logic

### **2xCBC2** mini-module + sensor

- Sr-90 source
- Cosmic rays
- Beam Test







# **Single Chip Results**



60

5fC

60

sweep global comparator threshold VCTH to get s-curves for range of test pulse amplitudes

plot s-curve mid-points vs. TP amp

rough calculation in 1÷2fC region (assumes TP value of 12 / fC)

(\* from VCTH bias sweep measurements)

### **Noise & Power**

		1200	electrons				400	0		
Analog:	130 + (21 x C <sub>in</sub> [pF]) μW	1000	mode			•	- 350	0We		
Digital: Trig. logic:	50μW	<b>1008</b>			)		- 300	ir/ch		
Total:	<230 + (21 x C <sub>in</sub> [pF]) μW	<u>م</u> 600		4		)	- 250	an.		
APV25	~2.6mW (long strips)	<b>50</b> 400			)		200			
		200		$\mathcal{I}$	Image: Apple of the second		150	150		
		200	$\bigcirc$		O∕Osi	mulation				
		0					<u> </u>			
		(	) 2	4 6	6 8	3 10	12			
			external capacitance [pF]							

#### noise & analogue power vs. external capacitance

- Noise and power depends on external input capacitance •
- The current settings in the front-end are adjusted to maintain the same pulse shape • for different C<sub>in</sub>
- Results almost identical for e<sup>-</sup> and h<sup>+</sup>

 $\rightarrow$  Within specification with ~800e<sup>-</sup><sub>RMS</sub> for 5pF strips at <325 $\mu$ W/channel

## **S-Curves and Tuning**



CBC2 channel no.

## **Results with On Chip Test Pulse**





→ Test pulse together with individually-programmable channel masks can be used to fully exercise the coincidence logic

# **Mini Module Results**

### Logic tests using beta source















## **Beam test results**



**Incident Angle** 

# **Future Work**

# **Future Work**

- Further testing of CBC2 up to 50 Mrad TID
- Testing for SE effects UC Louvain's cyclotron with protons (~50MeV)

### CBC3 (Final Prototype)

- Front End:
  - Adjust pre-amp (1V operation, single polarity, AC coupled & larger sensor capacitance)
  - Extra Comparator -- 3σ Threshold
  - ✤ Additional circuit to suppress HIPs
- **\*** Increase Pipeline to 12μs (possibly 25μs)
- Stub finding logic:
  - ♦  $\frac{1}{2}$  strip cluster resolution  $\rightarrow$  8 bit stub address
  - 5 bit bend information
  - Priority selection of 3 highest-pT stubs
  - Offset correction: 4 domains/chip (2 in CBC2)

### Stub readout:

- 13 bit/stub with up to 3 stubs/Bunch Crossing
- Data Output: 6 SLVS differential pairs @ 320Mbps
- Possible change to bump pad layout (Adjust for increased pitch)

# **Summary & Conclusions**

Two successful full-size prototypes of new Outer

### **Tracker ASIC**

- ✓ CBC2 working to specs
- ✓ Some front-end improvements over CBC1
- ✓ Stub finding logic functioning
- ✓ Power features (LDO & DC-DC) operational

#### First prototype version of 2S module in hand

- ✓ First demonstration of bump-bonded ASIC for strip readout
- ✓ Ready to be distributed to collaborating institutes
- ✓ First beam test followed by ionizing radiation studies



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**CERN**: S. Michelis, F. Faccio, K. Kloukinas

Many others for the beam test...





## **Total Ionizing Dose test**

- First xray irradiation to 10 Mrads
- CBC2 operated continuously during irradiation
- monitored currents, biases, pedestal, noise
- no significant change in performance, moderate increase in current before annealing
- Next: TID test up to 50 Mrads

![](_page_32_Picture_6.jpeg)

![](_page_32_Picture_7.jpeg)

![](_page_32_Picture_8.jpeg)

### **Noise & Power**

		1200	elec	trons				- 4	00	ξ
Analog:	130 + (21 x C <sub>in</sub> [pF]) μW	1000		oae				3	50	
Digital:	50μW <50μW	<b>800</b>		é		+		- 3	00	1/25
Total:	<230 + (21 x C <sub>in</sub> [pF]) μW	<mark>9</mark> 600	(	)		$\bigcirc$		- 2	50	3
APV25	~2.6mW (long strips)	2 400				,		2	00 🛓	
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		Ŭ	) 2	2 4	6	8	10	12	00	
		external capacitance [pF]								

#### noise & power vs. external capacitance

- Noise and power depends on external input capacitance
- The current settings in the front-end are adjusted to maintain the same pulse shape for different C<sub>in</sub>
- Results almost identical for e<sup>-</sup> and h<sup>+</sup>

 $\rightarrow$  specification of 1000e<sup>-</sup><sub>RMS</sub> for 5cm strips met with 350µW/channel

![](_page_34_Picture_0.jpeg)

## **Power distribution**

NB: the last column of PADs to the right are wire-bondable, they will not be routed on hybrid (->possible to reach the 3 pads to their left)

All but 160MHz output pads have redundancy

lines and arrows show direction of power flow (GND not shown)

note:

DC-DC 1.2 not connected to VDDD or VLDOI on-chip

LDO output also connected to VDDA offchip

(the idea is to maximise possible effectiveness of off-chip filtering)

Inputs dummy prev/next chip gnd

![](_page_34_Picture_10.jpeg)